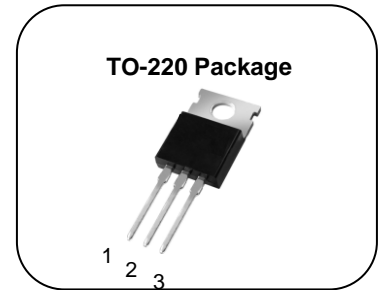
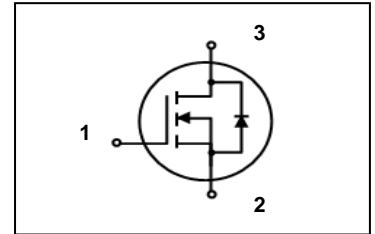


### Description

The XM120M80CX0LG uses advanced trench technology and Design to provide excellent RDS(ON) with low gate charge. The device is suitable for use in PWM, load switching and general Purpose applications



1. Gate 2. Drain 3. Source



### Features

- 80V,120A
- RDS(on)=6.5mΩ(Typ.) @VGS=10V,ID=20A
- Pb-free lead plating; RoHS compliant

### Absolute Maximum Ratings (Tc= 25°C unless otherwise noted.)

Symbol	Parameter	Value	Units
V <sub>DSS</sub>	Drain-Source Voltage	80	V
V <sub>GSS</sub>	Gate-Source Voltage	±20	V
I <sub>D</sub>	Continuous Drain Current ( T <sub>c</sub> =25 °C)	120	A
I <sub>DM</sub> <sup>1</sup>	Pulsed Drain Current	480	A
I <sub>F</sub>	Diode Continuous Forward Current ( T <sub>c</sub> =25°C)	120	A
P <sub>D</sub>	Power Dissipation ( T <sub>c</sub> =25 °C)	137	W
E <sub>AS</sub>	Avalanche Energy, Single pulse (V <sub>DD</sub> =40V,V <sub>GS</sub> =10V,L=0.5mH,R <sub>G</sub> =25Ω)	342	mJ
T <sub>J</sub>	Operating Junction Temperature Range	-55 to 150	°C
T <sub>STG</sub>	Storage Temperature Range	-55 to 150	°C

### Thermal Data

Symbol	Parameter	Value	Units
R <sub>θJC</sub>	Thermal Resistance-Junction to case (Steady State)	0.91	°C/W
R <sub>θJA</sub>	Thermal Resistance-Junction to Ambient (Steady State)	58.5	°C/W

Note:

1 : Pulse width is limited by safe operating area. Pulse test ; pulse width ≤ 300μs, duty cycle ≤ 2%

## Electrical characteristic (@T<sub>J</sub> = 25°C, unless otherwise specified)

### Static characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Drain to source breakdown voltage	V <sub>(BR)DSS</sub>	80	--	--	V	V <sub>GS</sub> =0V, I <sub>D</sub> =250uA
Gate threshold voltage	V <sub>GS(TH)</sub>	2	--	4	V	V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250uA
Zero gate voltage drain current	I <sub>DSS</sub>	--	--	1	uA	V <sub>DS</sub> =64V, V <sub>GS</sub> =0V
Gate to source leakage current	I <sub>GSS</sub>	--	--	±100	nA	V <sub>GS</sub> =±20V, V <sub>DS</sub> =0V
Drain-source on-state resistance	R <sub>DS(On)</sub>	--	6.5	--	mΩ	V <sub>GS</sub> =10V, I <sub>D</sub> =20A

### Dynamic characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Input capacitance	C <sub>iss</sub>	--	5622	--	pF	V <sub>GS</sub> =0V, V <sub>DS</sub> =25V, F=1MHz
Output capacitance	C <sub>oss</sub>	--	410	--	pF	
Reverse transfer capacitance	C <sub>rss</sub>	--	184	--	pF	
Turn on delay time	t <sub>d(on)</sub>	--	19	--	ns	V <sub>DS</sub> =30V, R <sub>L</sub> =15Ω, R <sub>G</sub> =2.5Ω, V <sub>GS</sub> =10V
Rising time	T <sub>r</sub>	--	22	--	ns	
Turn off delay time	t <sub>d(off)</sub>	--	47	--	ns	
Fall time	t <sub>f</sub>	--	32	--	ns	
Total gate charge	Q <sub>g</sub>	--	106	--	nC	V <sub>DS</sub> =50V, V <sub>GS</sub> =10V I <sub>D</sub> =40A
Gate-source charge	Q <sub>gs</sub>	--	36	--	nC	
Gate-drain charge	Q <sub>gd</sub>	--	32	--	nC	

### Reverse diode characteristics

Parameter	Symbol	Values			Unit	Note/Test Condition
		Min.	Typ.	Max.		
Diode forward voltage	V <sub>SD</sub>	--	0.89	0.95	V	I <sub>F</sub> =20A, V <sub>GS</sub> =0V, T <sub>J</sub> = 25°C
Reverse recovery time	t <sub>rr</sub>	--	34	--	ns	I <sub>F</sub> =40A, V <sub>DS</sub> =30V dI <sub>F</sub> /dt=100A/us
Reverse recovery charge	Q <sub>rr</sub>	--	50	--	uC	
Peak reverse recovery current	I <sub>rrm</sub>	--	2.83	--	A	

## Electrical characteristics diagrams

Table 1

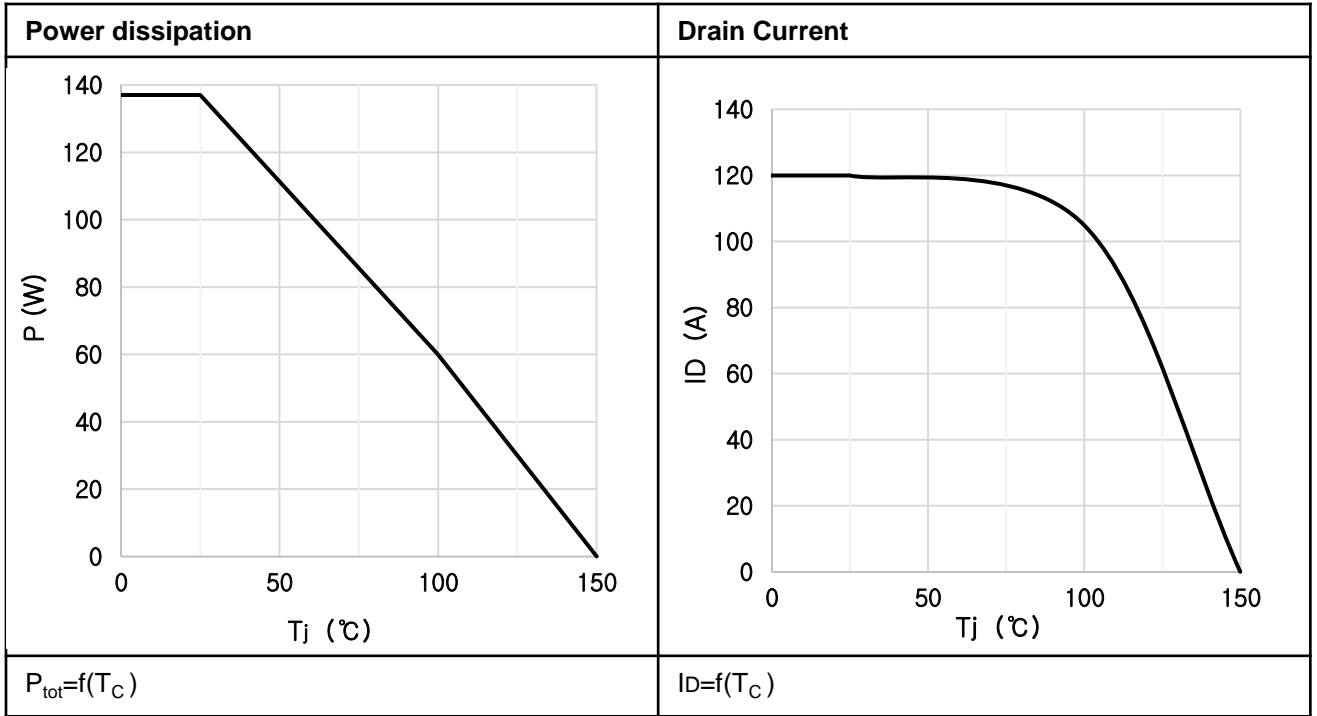


Table 2

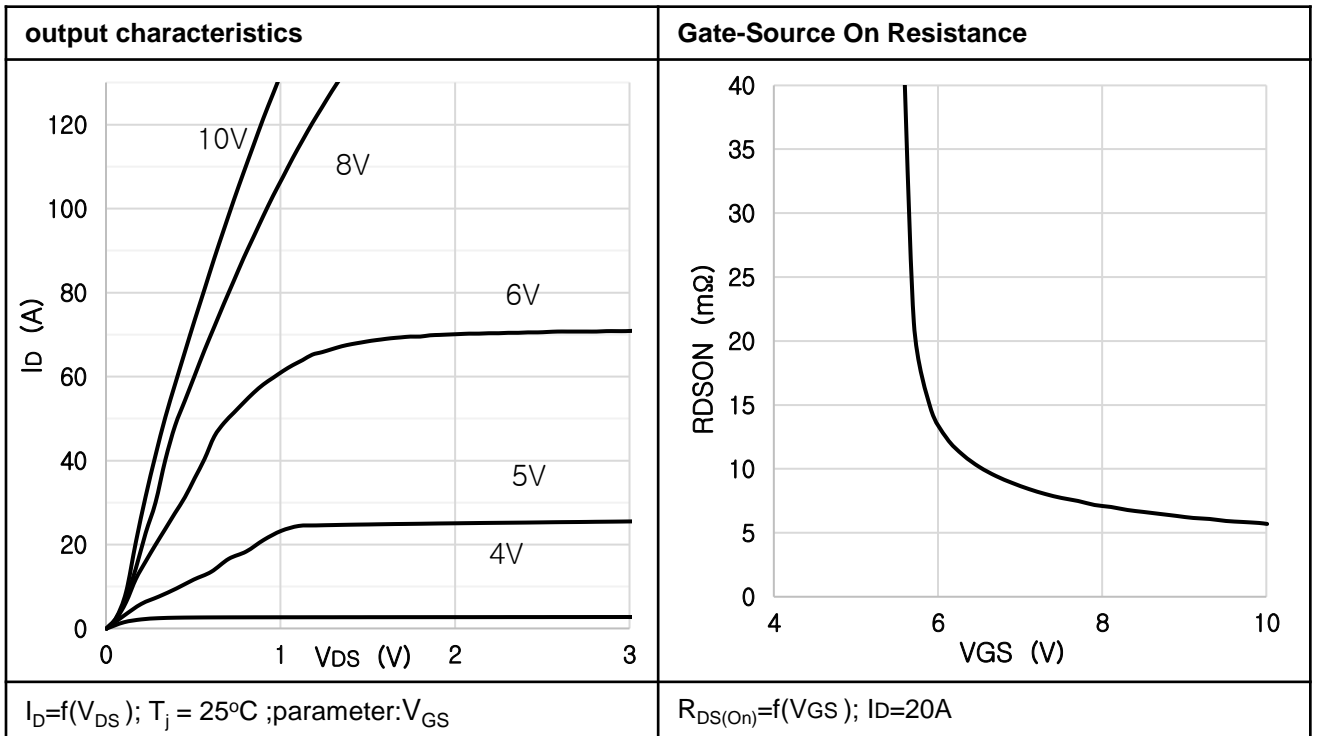


Table 3

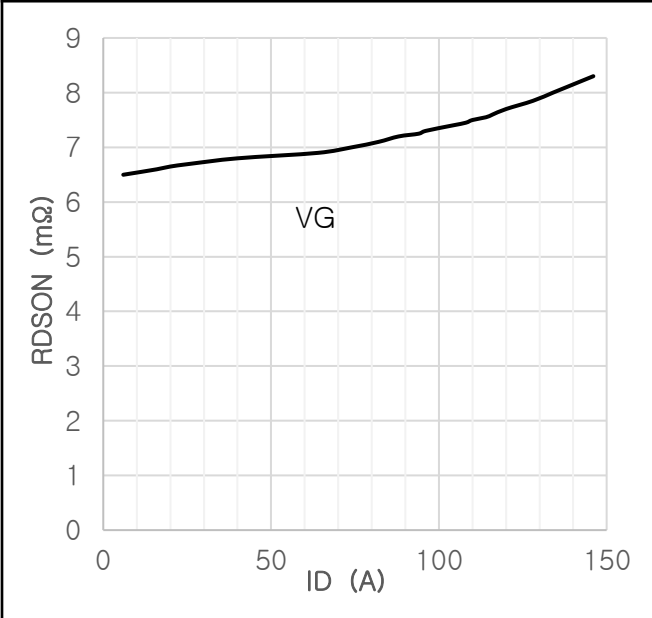
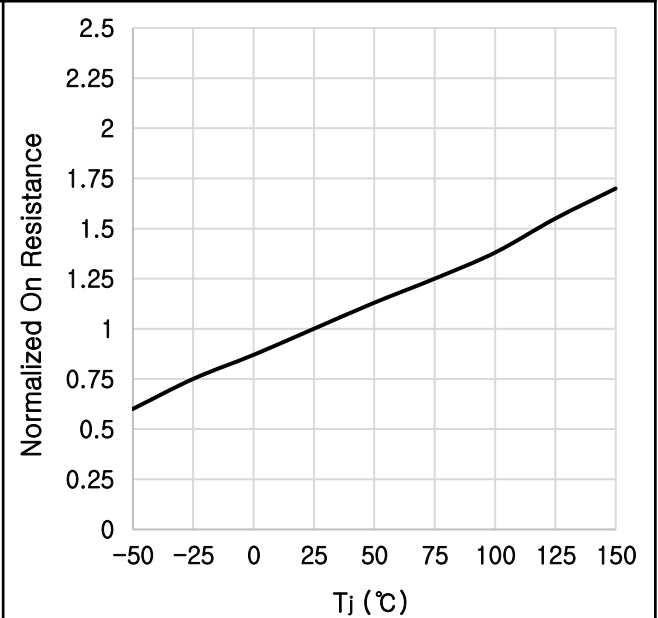
Drain-source on-state resistance	Drain-source on-state resistance
	
$R_{DS(on)}=f(I_D); V_{GS}=10V$	$R_{DS(on)}=f(T_j); I_D=20A; V_{GS}=10V$

Table 4

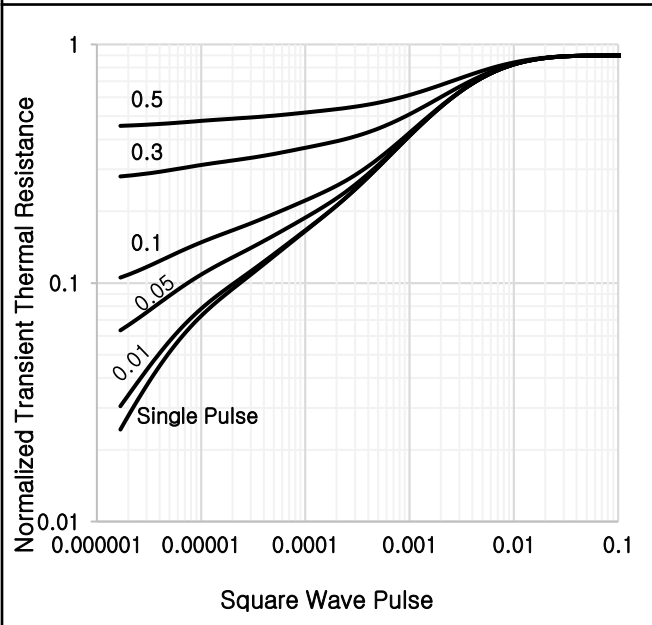
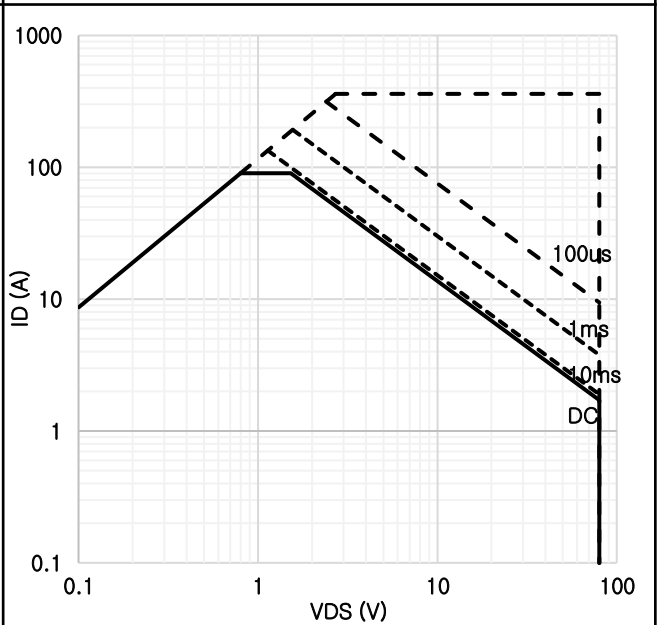
Thermal Transient Impedance	Safe operating area $T_C=25^\circ C$
	
$Z_{thJC}=f(t_p); \text{parameter: } D=t_p/T$	$I_D=f(V_{DS}); T_C=25^\circ C; D=0; \text{parameter: } t_p$

Table 5

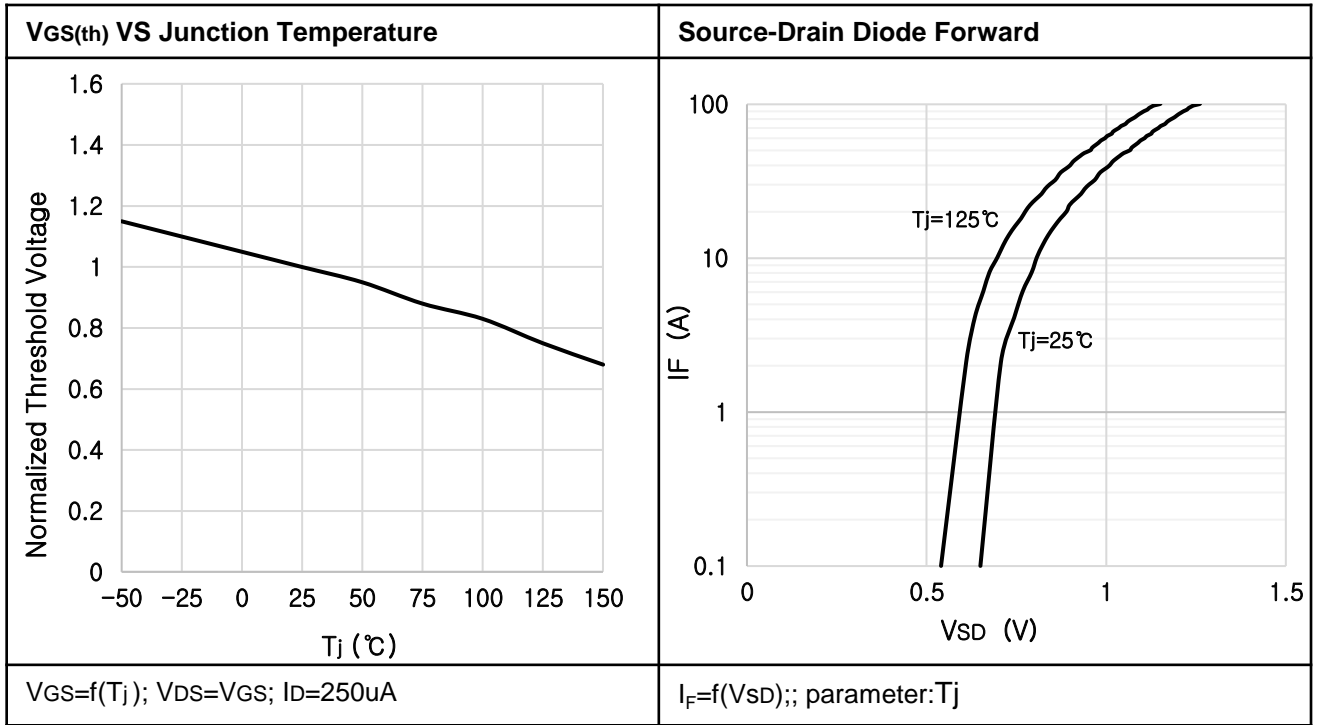
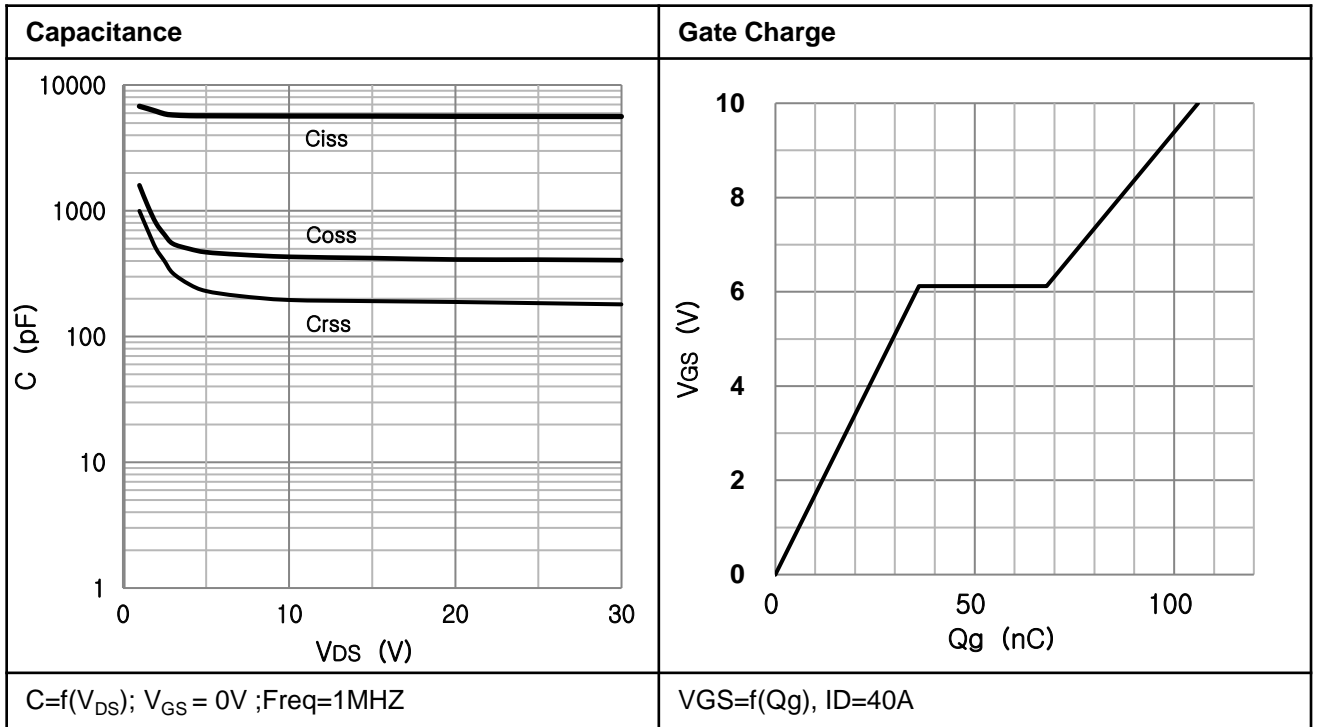
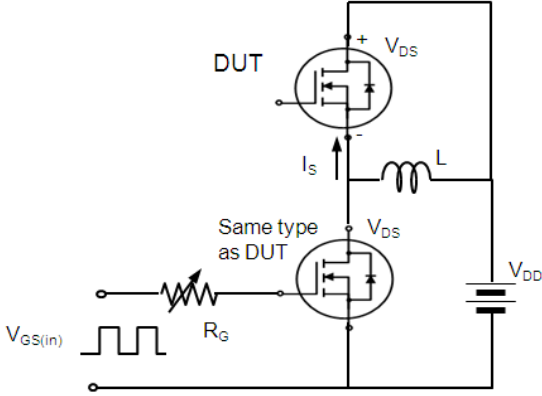
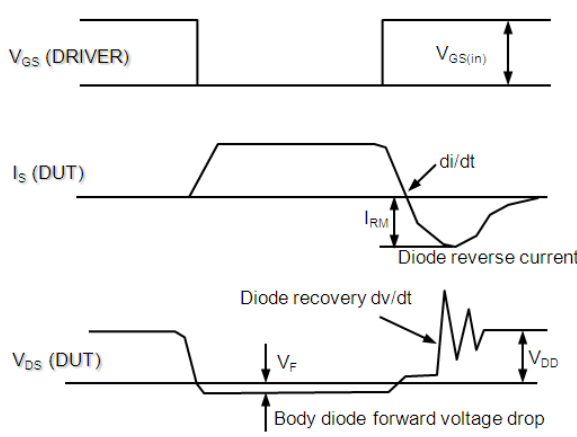


Table 6

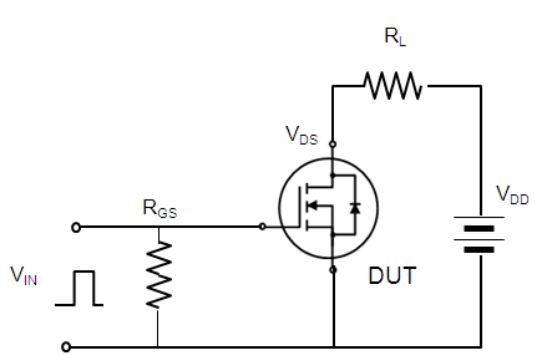
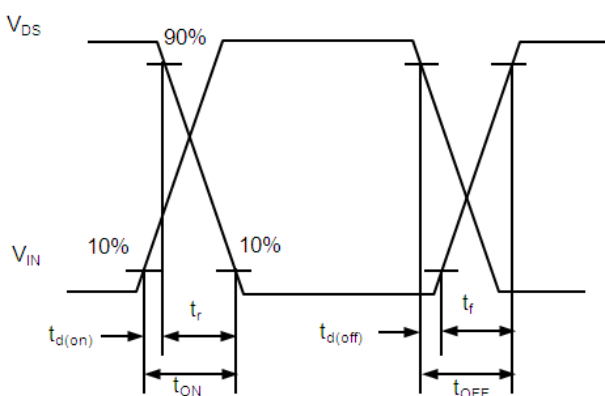


## Test Circuit & Waveform

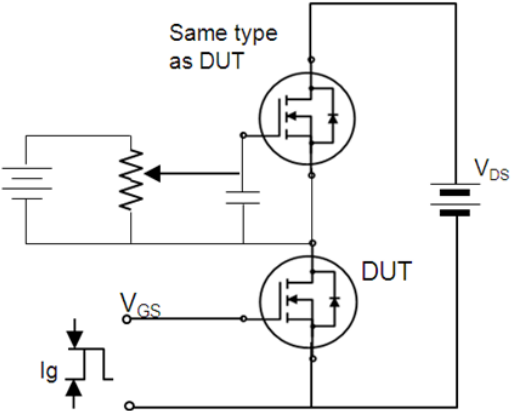
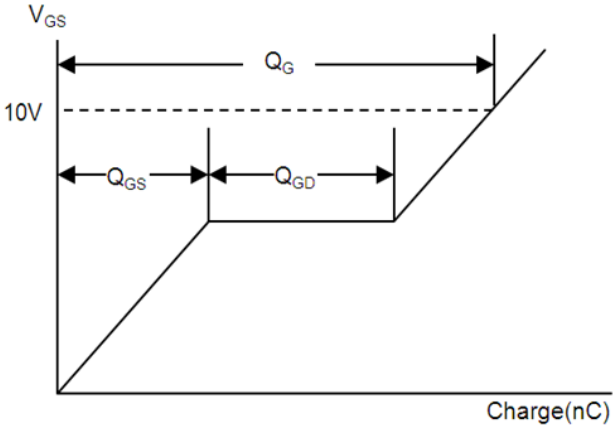
**Table 7 Diode Recovery Characteristic**

Test Circuit For Diode Recovery	Test Waveform For Diode Recovery
 <p>*. <math>dv/dt</math> controlled by <math>R_G</math>          *. <math>I_S</math> controlled by pulse period</p>	

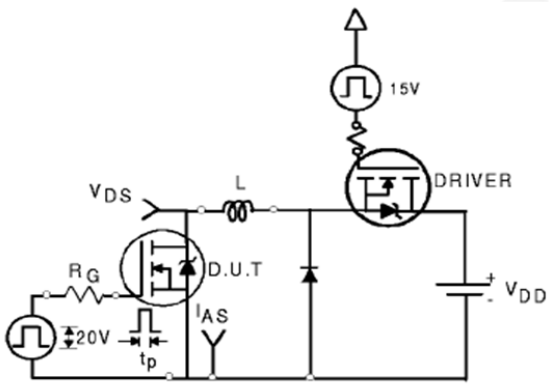
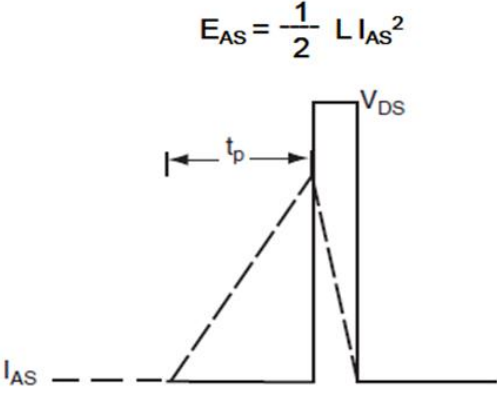
**Table 8 Switching Time Characteristic**

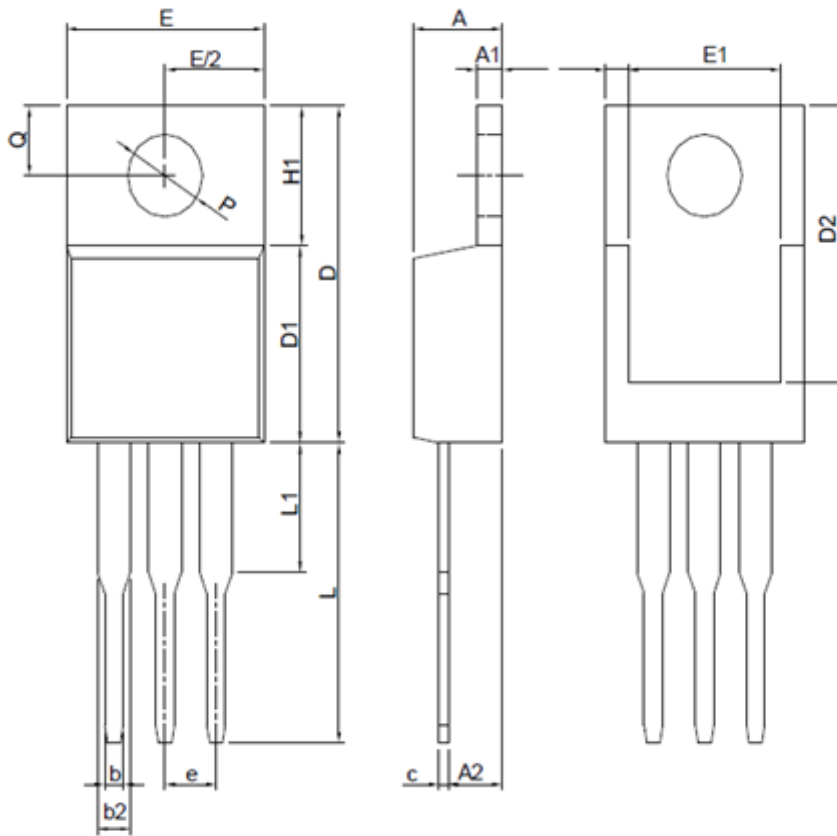
Test Circuit for Switching Time	Test Waveform for Switching Time
	

**Table 9 Gate Charge Characteristic**

Test Circuit For Gate Charge	Test Waveform For Gate Charge
	

**Table 10 Unclamped Inductive Characteristic**

Test Circuit For Unclamped Inductive	Test Waveform For Unclamped Inductive
	 $E_{AS} = \frac{1}{2} L I_{AS}^2$



SYMBOLS	TO-220			
	MILLIMETERS		INCHES	
	MIN.	MAX.	MIN.	MAX.
A	3.56	4.83	0.140	0.190
A1	0.51	1.40	0.020	0.055
A2	2.03	2.92	0.080	0.115
b	0.38	1.02	0.015	0.040
b2	1.14	1.78	0.045	0.070
c	0.36	0.61	0.014	0.024
D	14.22	16.51	0.560	0.650
D1	8.38	9.02	0.330	0.355
D2	12.19	13.65	0.480	0.537
E	9.65	10.67	0.380	0.420
E1	6.86	8.89	0.270	0.350
e	2.54 BSC		0.100 BSC	
H1	5.84	6.86	0.230	0.270
L	12.70	14.73	0.500	0.580
L1	-	6.35	-	0.250
P	3.53	4.09	0.139	0.161
Q	2.54	3.43	0.100	0.135

Note: Follow JEDEC TO-220 AB.

↑



## Revision History

Ver.	Date	Change Notice
1.0	2019/10/15	Release